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PATENT APPLICATION



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of:

Shigeyuki UEDA

Application No.: 09/665,663

Filed: September 20, 2000

For: SEMICONDUCTOR CHIP AND METHOD OF PRODUCING THE SAME

Attorney Docket No.: ROH-026

Examiner: W. D. Coleman

Art Unit: 2823

Confirmation No.: 5545

TECHNOLOGY CENTER 2800

SEP - 5 2002

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PRELIMINARY AMENDMENT

BOX RCE

Commissioner for Patents
Washington, D.C. 20231

Sir:

Prior to examination on the merits after filing the accompanying Request for Continued Examination filed in response to the final Office Action dated May 30, 2002, please amend the above-identified application as follows:

IN THE CLAIMS:

Please cancel claims 1, 6, 8 and 9 without prejudice or disclaimer.

Please amend claims 2, 7 and 10 as set forth below in clean form. Additionally, in accordance with 37 CFR 1.121(c)(1)(ii), amended claim(s) is/are set forth in a marked-up version in the page(s) attached to this Amendment.

2. (Amended) The semiconductor chip according to claim 11, wherein

B1 said semiconductor chip is overlapped with and joined to a surface of another solid device in a state where said surface protective film is opposed to a surface of the solid device.

7. (Twice Amended) The semiconductor chip according to claim 12,

B2 wherein

said wire connecting portion is composed of the same material as that for said electrical contact projection.